

ABSTRACT OF THE DISCLOSURE

A semiconductor device of the present invention includes a film-like flexible substrate having formed thereon a wiring pattern, external connection terminals formed at both end portions of the flexible substrate; and a semiconductor element mounted on a surface side of the flexible substrate, wherein a folded part, which is folded down in U-shape to a back surface side of the flexible substrate, is formed in a fixed state at least at one end portion of the flexible substrate. With this structure, the semiconductor device is COF mounted, and, for example, in its application to a liquid crystal module wherein the semiconductor device is provided so as to face a liquid crystal panel, the external connection terminals of the flexible substrate can be connected to an inner surface of a module main body for a liquid crystal panel in a state the semiconductor element of the semiconductor device faces the inside of the module main body. As a result, since the semiconductor element can be mounted without being projected to the outside of the module main body, the liquid crystal module can be made thinner for the thickness of the semiconductor element.